

SiC N-MOSFET 1200V, 75mΩ, 30A

## Features

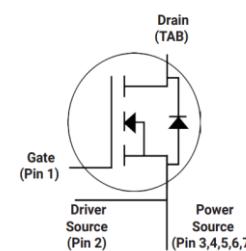
- High Blocking Voltage with Low On-Resistance
- High Speed Switching with Low Capacitances
- Avalanche Ruggedness

## Product Summary

V <sub>DS</sub>	1200V
R <sub>DS(on)_typ</sub>	75mΩ
I <sub>D</sub>	30A

## Applications

- Solar Inverters
- Switch Mode Power Supplies
- High Voltage DC-DC Converters
- Battery Chargers



## Package Marking and Ordering Information

Part #	Marking	Package
T1M80120J	1M80120J	TO-263-7

## Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Drain-source voltage	V <sub>DS</sub>	1200	V
Continuous drain current T <sub>C</sub> = 25°C , V <sub>GS</sub> =18V T <sub>C</sub> = 100°C , V <sub>GS</sub> =18V	I <sub>D</sub>	30 21	A
Source current(Body Diode) T <sub>C</sub> = 25°C , V <sub>GS</sub> =-4V T <sub>C</sub> = 100°C , V <sub>GS</sub> =-4V	I <sub>S</sub>	30 21	A
Pulsed drain current (T <sub>C</sub> = 25°C, t <sub>p</sub> limited by T <sub>jmax</sub> )	I <sub>D</sub> pulse	80	A
Avalanche energy, single pulse (L=10mH)	E <sub>AS</sub>	600	mJ
Gate-Source voltage	V <sub>GS</sub>	-4/+18	V
Gate-Source voltage (Absolute maximum values)	V <sub>GSmax</sub>	-8/+22	V
Power dissipation (T <sub>C</sub> = 25°C)	P <sub>tot</sub>	136	W
Operating junction and storage temperature	T <sub>j</sub> , T <sub>stg</sub>	-55...+175	°C

- Example of acceptable V<sub>GS</sub> waveform



**Thermal Resistance**

Parameter	Symbol	Value	Unit
Thermal resistance, junction - case. Max	$R_{thJC}$	1.1	°C/W
Thermal resistance, junction - ambient. Max	$R_{thJA}$	40	

**Electrical Characteristic (at  $T_J = 25$  °C, unless otherwise specified)**

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		

**Static Characteristic**

Drain-source breakdown voltage	$V_{DSS}$	1200	-	-	V	$V_{GS}=0V, I_D=100\mu A$
Gate threshold voltage	$V_{GS(th)}$	2.3	2.8	3.6	V	$V_{DS}=V_{GS}, I_D=5mA$
Zero gate voltage drain current	$I_{DSS}$	-	1	10	$\mu A$	$V_{DS}=1200V, V_{GS}=0V$
		-	5	-		$T_J=25^\circ C$
		-	-	-		$T_J=175^\circ C$
Gate-source leakage current	$I_{GSS}$	-		100	nA	$V_{GS}=18V, V_{DS}=0V$
Drain-source on-state resistance	$R_{DS(on)}$	-	75	85	$m\Omega$	$V_{GS}=18V, I_D=20A,$
		-	125	-		$T_J=25^\circ C$
		-	-	-		$T_J=175^\circ C$
Transconductance	$g_{fs}$	-	10	-	S	$V_{DS}=20V, I_D=20A$

**Dynamic Characteristic**

Input Capacitance	$C_{iss}$	-	920	-	pF	$V_{DS} = 1000V$ $V_{GS} = 0V$ $T_J = 25^\circ C$ $V_{AC} = 25mV$ $f = 1MHz$
Output Capacitance	$C_{oss}$	-	57	-		
Reverse Transfer Capacitance	$C_{rss}$	-	3.9	-		
Gate Total Charge	$Q_G$	-	40	-	nC	$V_{DS} = 800V$ $V_{GS} = -4/18V$ $I_D = 20A$
Gate-Source charge	$Q_{gs}$	-	7	-		
Gate-Drain charge	$Q_{gd}$	-	19	-		
Turn-On Switching Energy	$E_{ON}$	-	320	-	$\mu J$	$V_{DD} = 800V$ $V_{GS} = -4/+15V$ $I_D = 20A$ $R_G = 0\Omega$ $L = 120\mu H$
Turn-Off Switching Energy	$E_{OFF}$	-	49	-		
Turn-on delay time	$t_{d(on)}$	-	19	-		
Rise time	$t_r$	-	21	-	ns	
Turn-off delay time	$t_{d(off)}$	-	15	-		
Fall time	$t_f$	-	17	-		
Gate resistance	$R_G$	-	1.5	-	$\Omega$	$V_{AC} = 25mV, f=1MHz$

**Body Diode Characteristic**

<b>Parameter</b>	<b>Symbol</b>	<b>Value</b>			<b>Unit</b>	<b>Test Condition</b>
		<b>min.</b>	<b>typ.</b>	<b>max.</b>		
Body Diode Forward Voltage	$V_{SD}$	-	4.2	-	V	$V_{GS}=-4V, I_{SD}=10A, T_J=25^{\circ}C$
		-	3.8	-		$V_{GS}=-4V, I_{SD}=10A, T_J=175^{\circ}C$
Body Diode Forward Current	$I_{SD}$	-	-	30	A	$V_{GS}=-4V, T_J=25^{\circ}C$
Pulsed Body Diode Forward Current	$I_{SDM}$	-	-	89		
Reverse Recovery Time	$t_{rr}$	-	39.6	-	ns	$V_R = 800V, V_{GS} = -4V, I_D = 20A, di/dt = 700A/\mu S, T_J = 25^{\circ}C$
Reverse Recovery Charge	$Q_{rr}$	-	141.1	-	nC	
Reverse Recovery Energy	$E_{REC}$	-	62.9	-	uJ	
Peak Reverse Recovery Current	$I_{rrm}$	-	6.2	-	A	
Charge Time	$t_A$	-	9.9	-	ns	
DisCharge Time	$t_B$	-	29.7	-	ns	
Reverse Recovery Time	$t_{rr}$	-	45.4	-	ns	$V_R = 800V, V_{GS} = -4V, I_D = 20A, di/dt = 700A/\mu S, T_J = 175^{\circ}C$
Reverse Recovery Charge	$Q_{rr}$	-	397	-	nC	
Reverse Recovery Energy	$E_{REC}$	-	180.1	-	uJ	
Peak Reverse Recovery Current	$I_{rrm}$	-	13.8	-	A	
Charge Time	$t_A$	-	30.8	-	ns	
DisCharge Time	$t_B$	-	14.9	-	ns	

## Typical Performance Characteristics

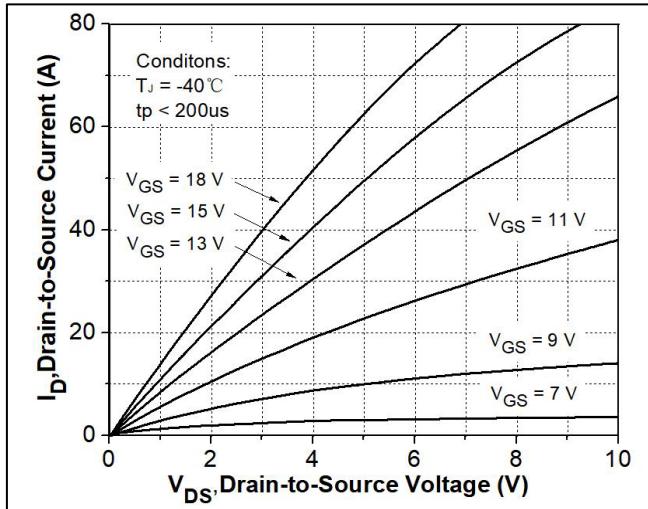
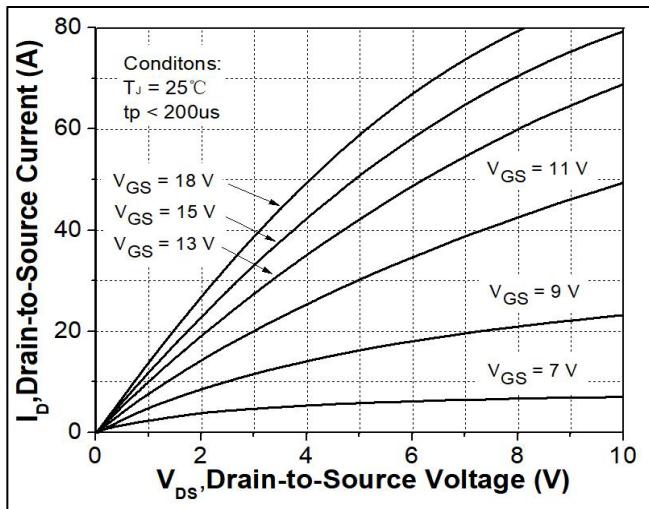
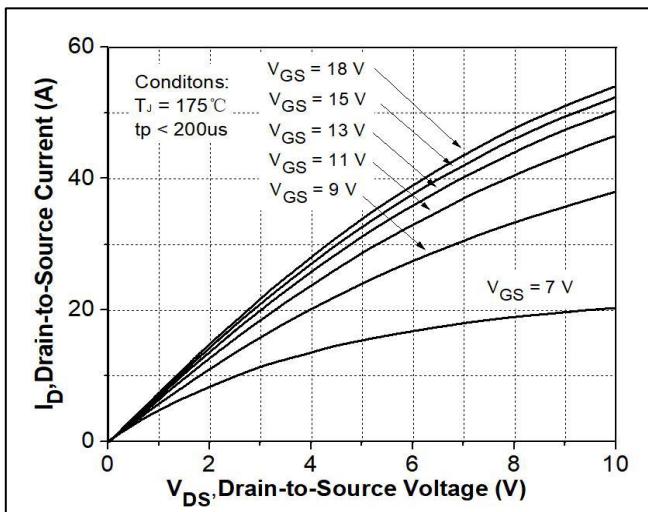
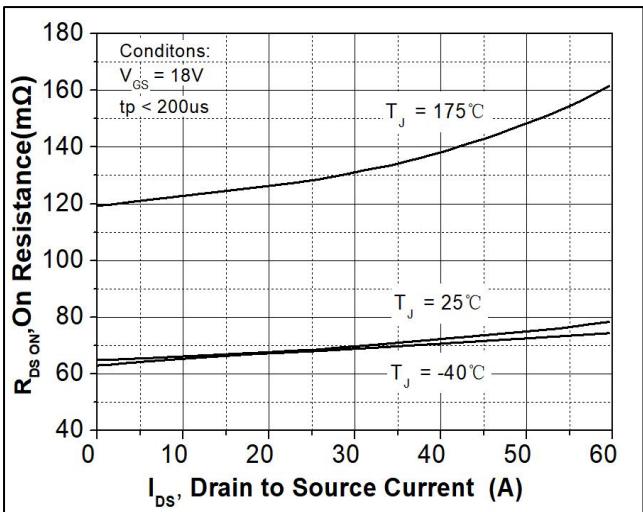
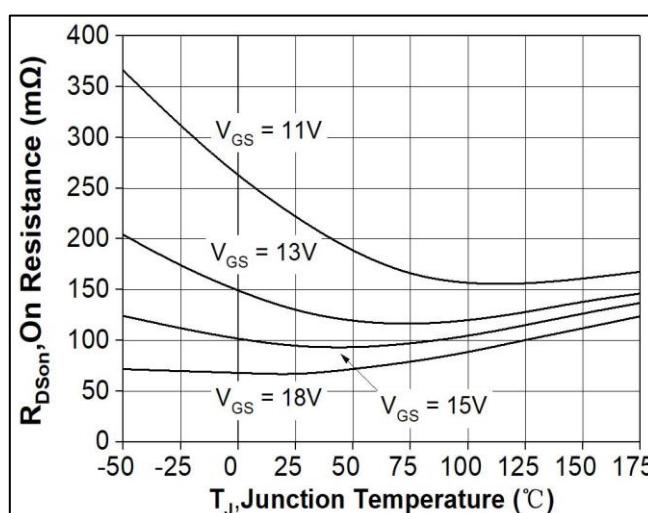
Fig 1. Output Characteristic ( $T_J = -40^\circ\text{C}$ )Fig 2. Output Characteristic ( $T_J = 25^\circ\text{C}$ )Fig 3. Output Characteristic ( $T_J = 175^\circ\text{C}$ )Fig 4:  $R_{dson}$  Vs  $I_{ds}$  CharacteristicFig 5:  $R_{dson}$  vs. Temperature

Fig 6: Transfer Characteristic

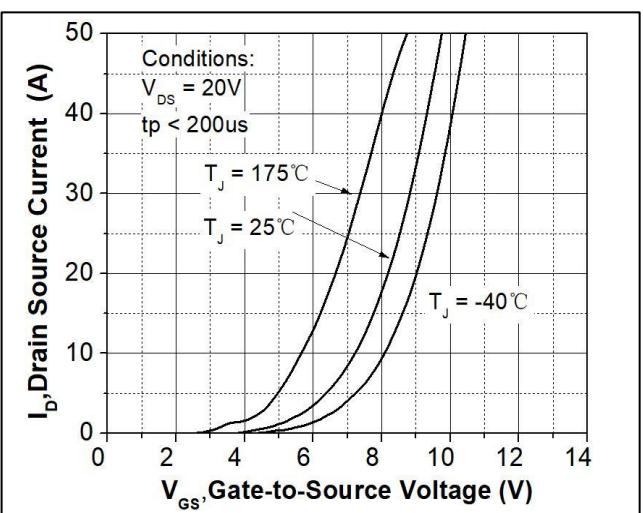


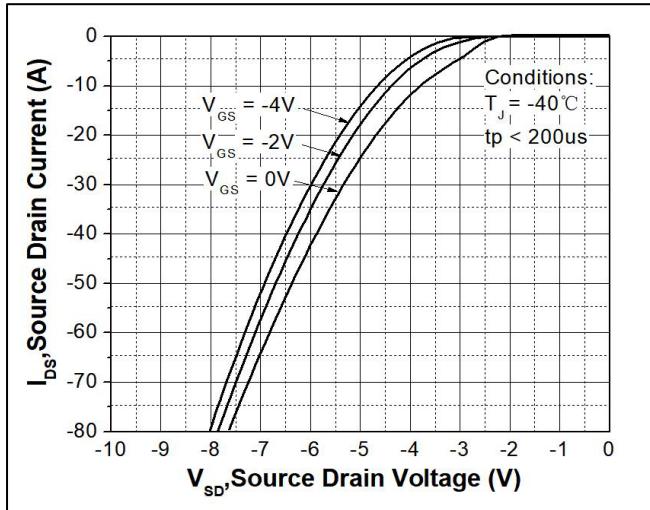
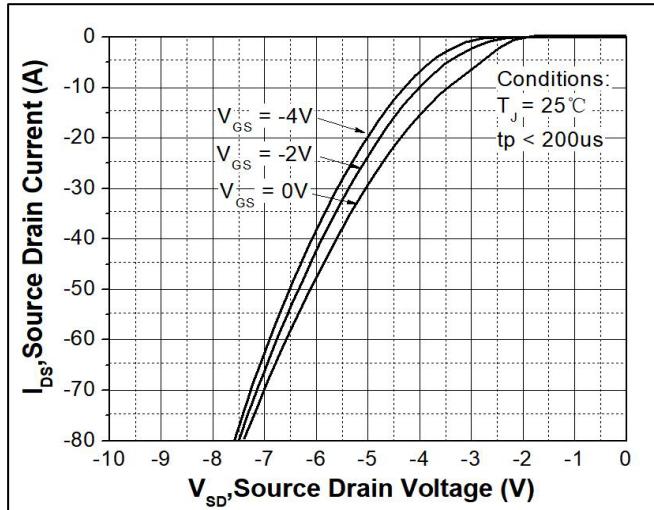
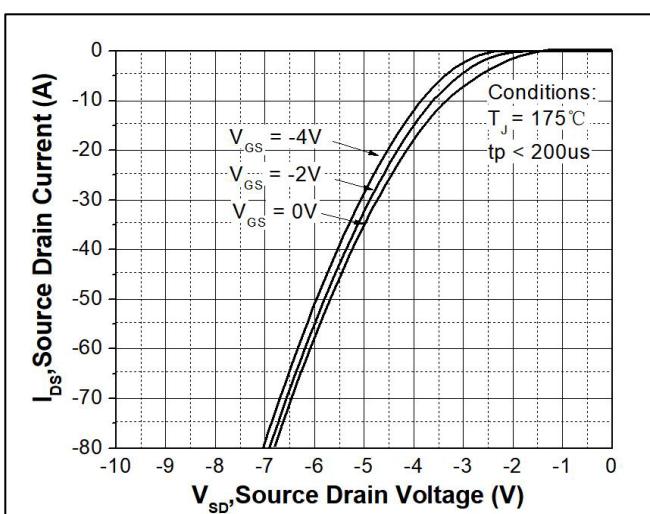
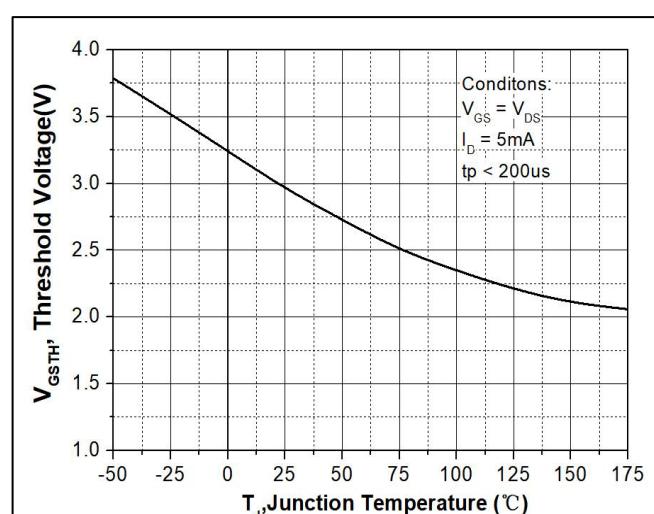
Fig 7: Body-diode Characteristic ( $T_J = -40^\circ\text{C}$ )Fig 8: Body-diode Characteristic ( $T_J = 25^\circ\text{C}$ )Fig 9: Body-diode Characteristic ( $T_J = 175^\circ\text{C}$ )Fig 10:  $V_{TH}$  Vs  $T_J$  Temperature Characteristic

Fig 11: Gate Charge Characteristics

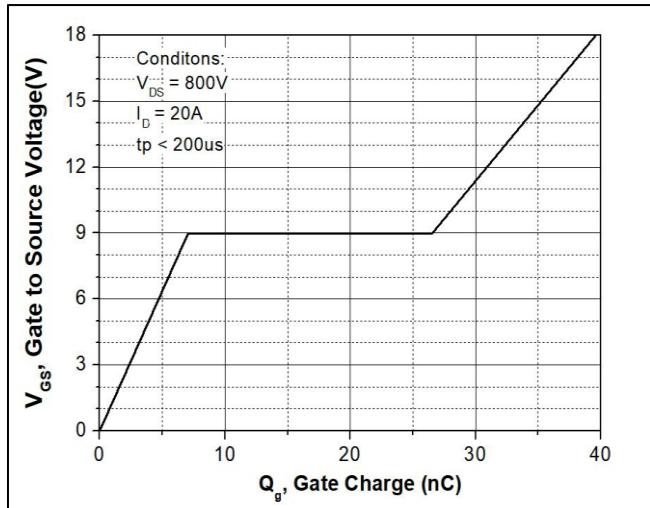
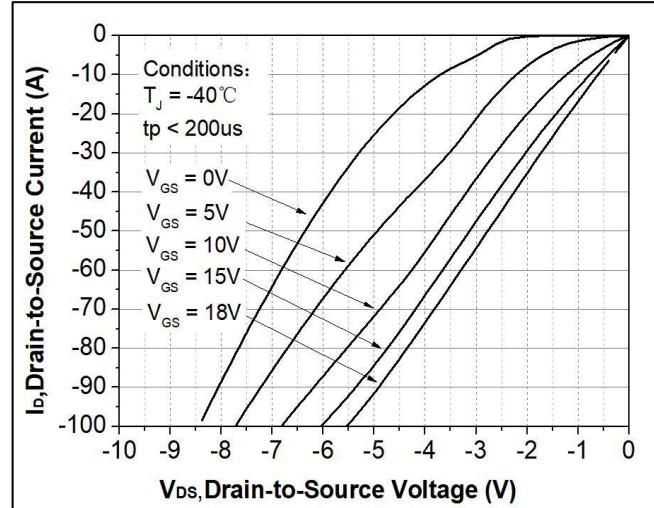
Fig 12: 3rd Quadrant Characteristic ( $T_J = -40^\circ\text{C}$ )

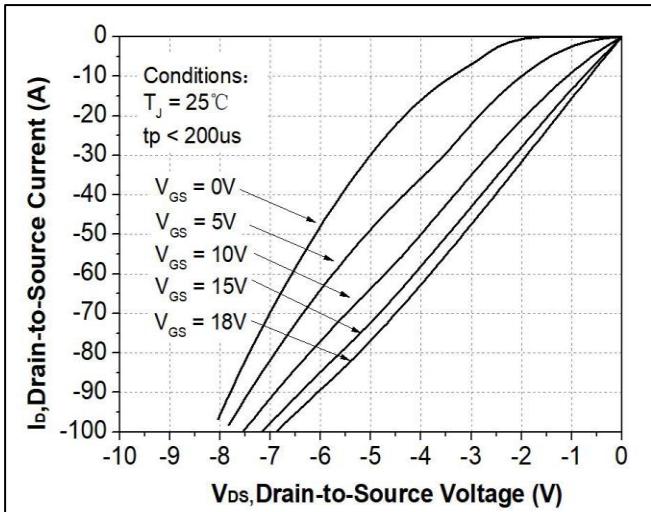
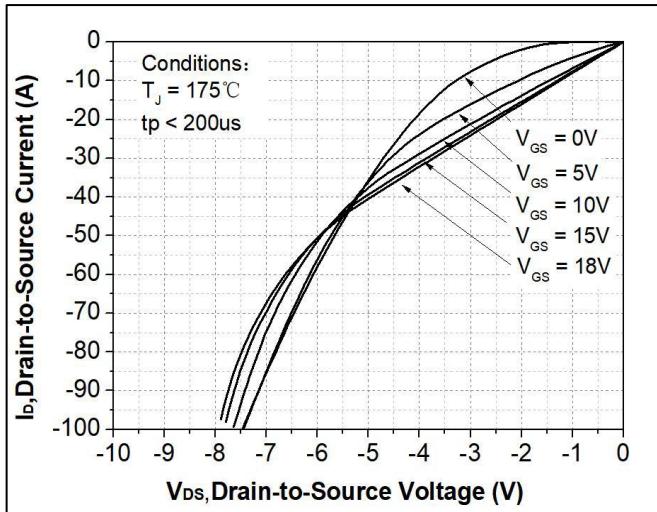
Fig 13: 3rd Quadrant Characteristic( $T_J=25^\circ\text{C}$ )Fig 14: 3rd Quadrant Characteristic( $T_J=175^\circ\text{C}$ )

Fig 15: Capacitance Characteristic

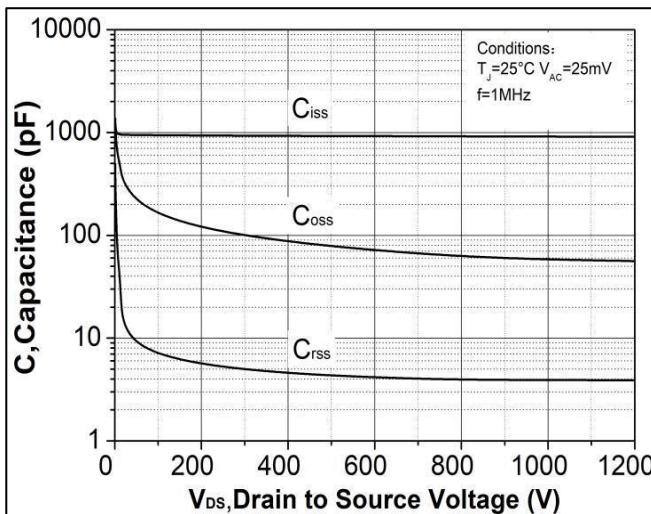


Fig 16: Safe Operating Area

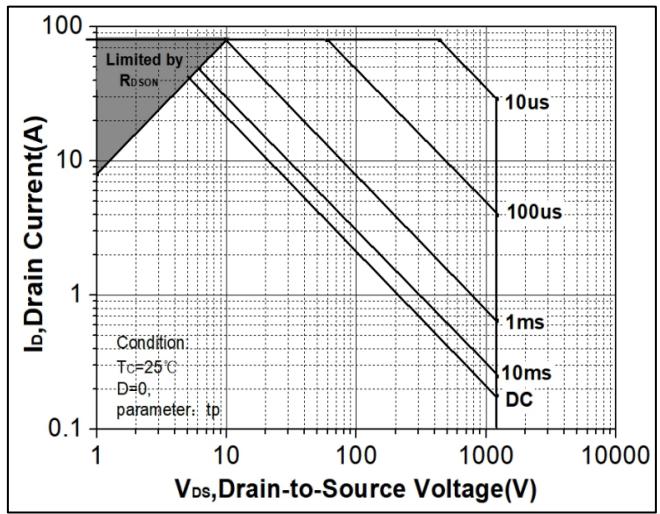
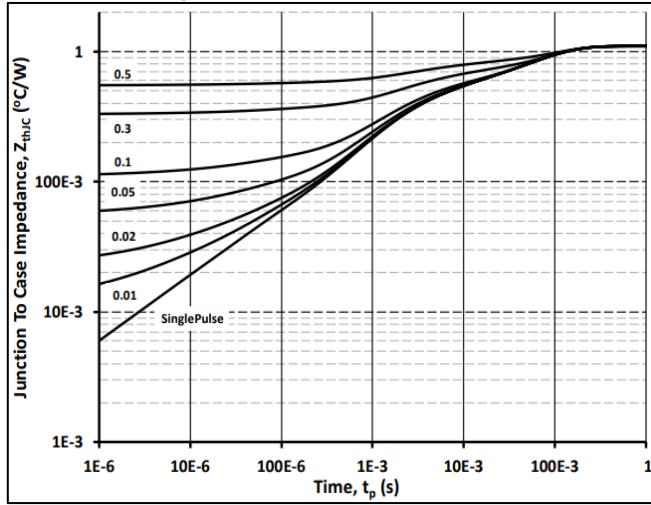


Fig 17: Transient Thermal Impedance



## Test Circuit & Waveform

Figure A. Definition of switching times

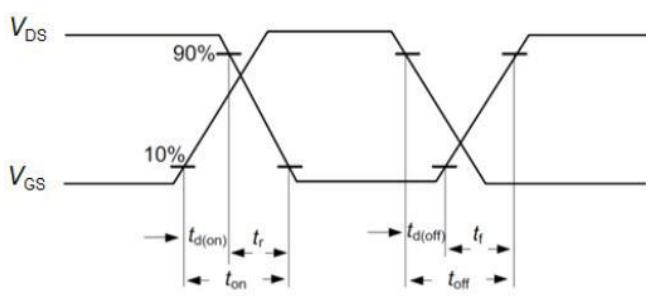


Figure B. Dynamic test circuit

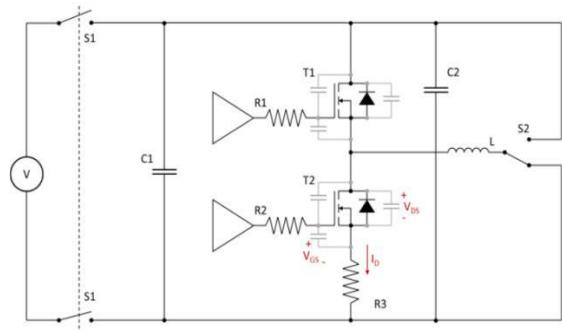


Figure C. Definition of body diodeswitching characteristics

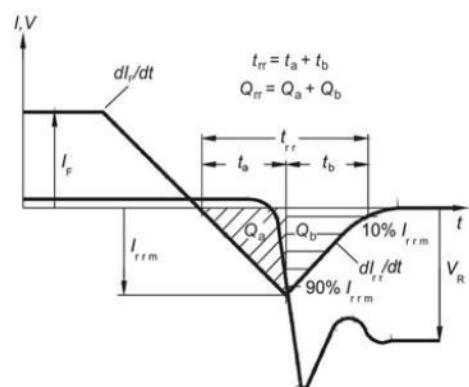
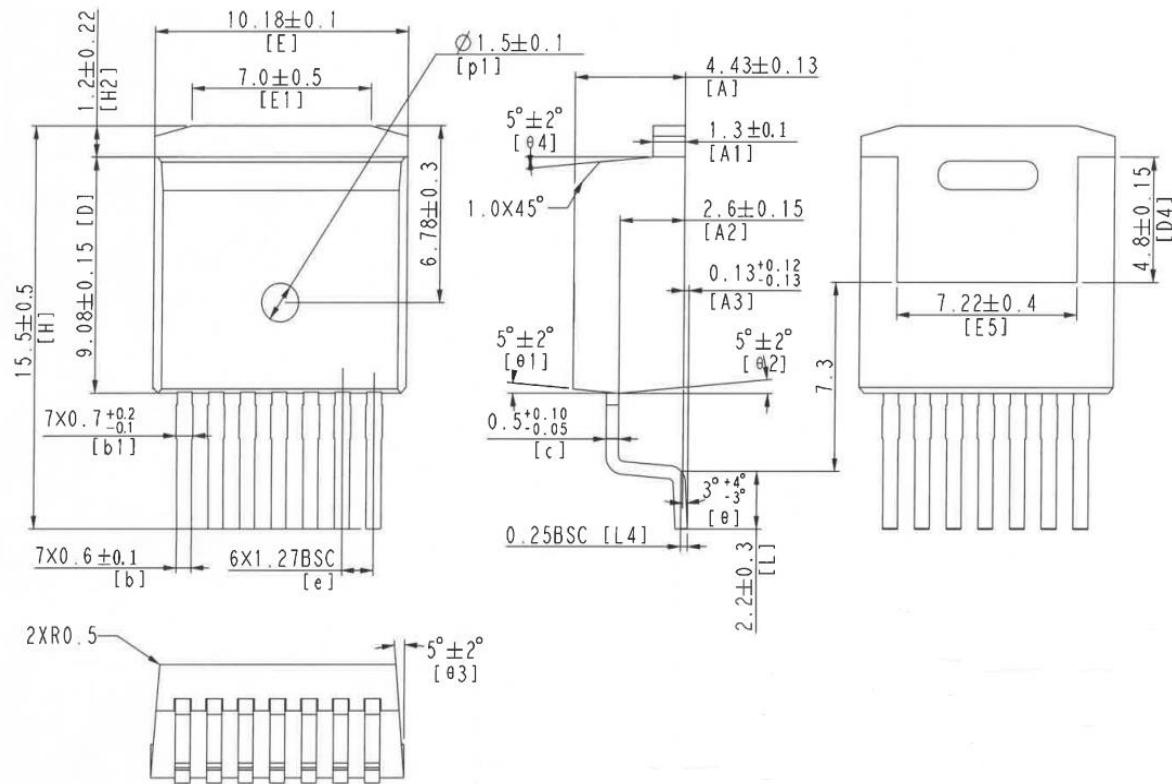


Figure C. Definition of diode switching characteristics

## Package Outline:

UNIT:mm



## Contact Information

TANI website: <http://www.tanisemi.com> Email:tani@tanisemi.com

For additional information, please contact your local Sales Representative.



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